

MA24F41

Silicon epitaxial planar type

For high speed switching circuits

■ Features

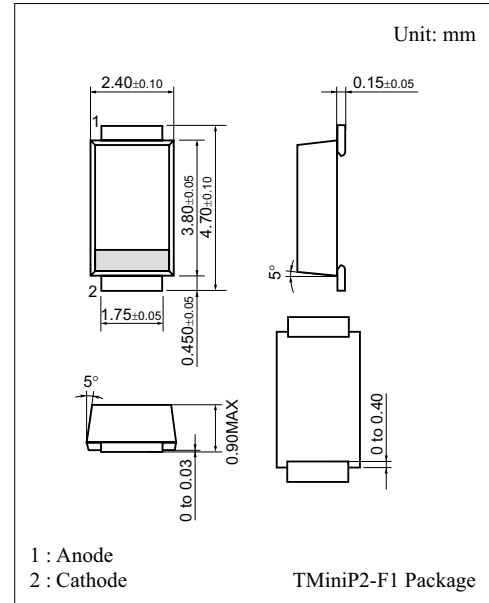
- Super high speed switching characteristic ($t_{rr} = 15$ nsec typ.)
- At the same time as lowering the wiring inductance and increasing the peak surge forward current, the resistance to surge damage at power on has been increased by adopting clip connection package (TMP).

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	400	V
Non-repetitive peak reverse surge voltage	V_{RSM}	400	V
Forward current *1	I_F	1.0	A
Non-repetitive peak forward surge current *2	I_{FSM}	20	A
Junction temperature	T_j	-40 to +150	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +150	$^\circ\text{C}$

Note) *1: Mounted on an alumina PC board

*2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)



Marking Symbol: G2

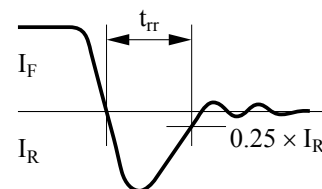
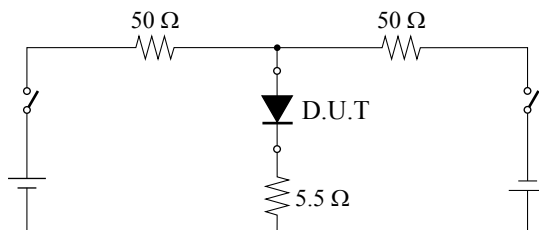
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

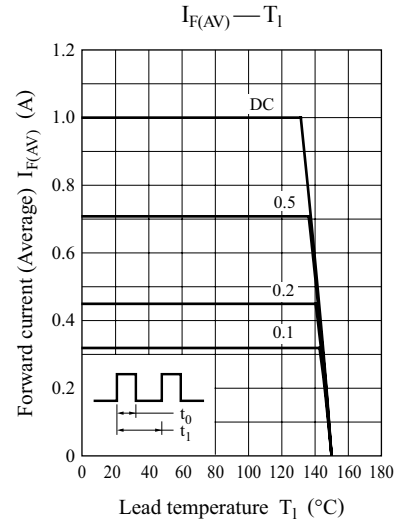
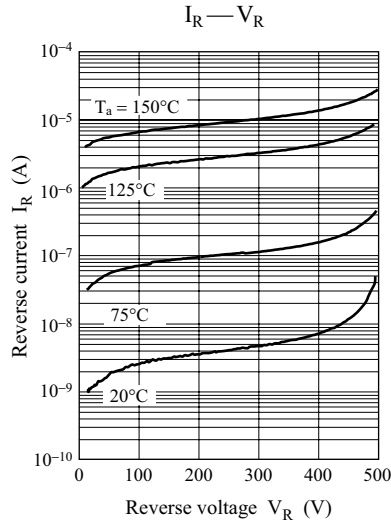
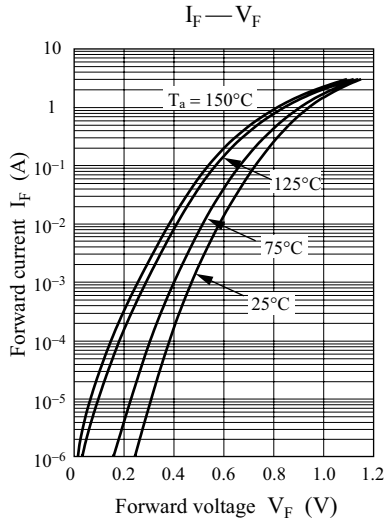
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 800$ mA		1.0	1.3	V
Reverse current	I_{RRM}	$V_{RRM} = 400$ V			20	μA
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz		30		pF
Reverse recovery time *	t_{rr}	$I_F = 0.5$ A, $I_R = 1.0$ A $I_{rr} = 0.25$ A		15	45	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 10 MHz.

3. *: t_{rr} measurement circuit





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